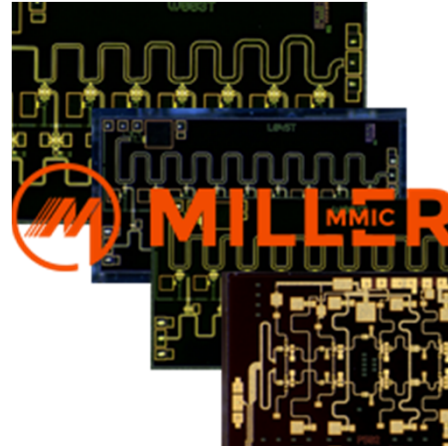


Features

- SPST Reflective design
- Frequency:DC-40GHz
- Isolation: 33dB
- Insertion Loss: 0.2dB~1.5dB
- Return Loss (ON):20dB
- Control Voltage:0/-5V
- Switching Speed: 15 ns
- Die Size: 1.1x0.75x 0.1 mm



Typical Applications

- Voltage control no current
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

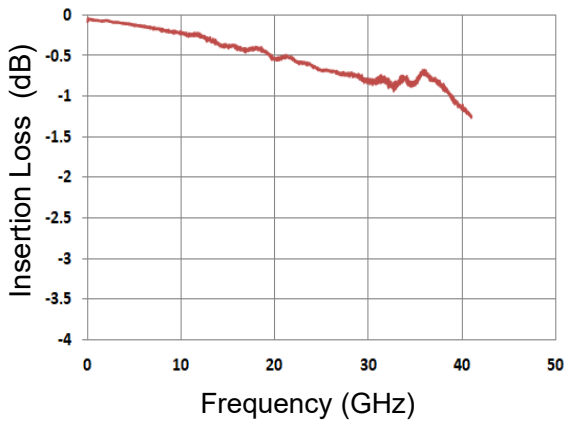
Electrical Specifications

TA = +25°C, VCTL=0/-5V

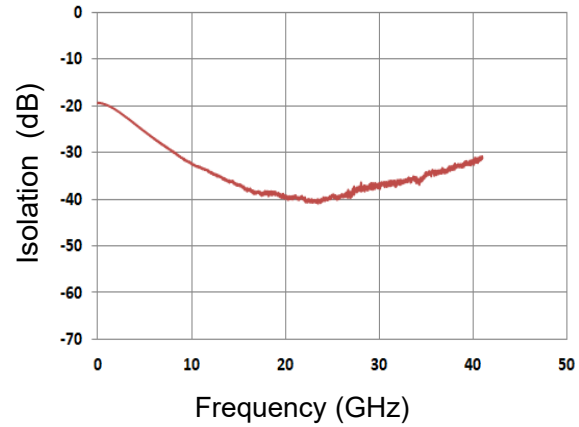
Parameters	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency	DC-6			6-18			18-40			GHz
Insertion Loss		0.2	0.3		0.3	0.5		0.8	1.5	dB
Isolation	18	25		30	35		30	35		dB
Return Loss (ON State)	30	35		25	30		16	18		dB
Input P-1		18			18			18		dBm
RF Input power			30			30			30	dBm
IIP3		28			28			28		dBm
Switching Speed	15									ns



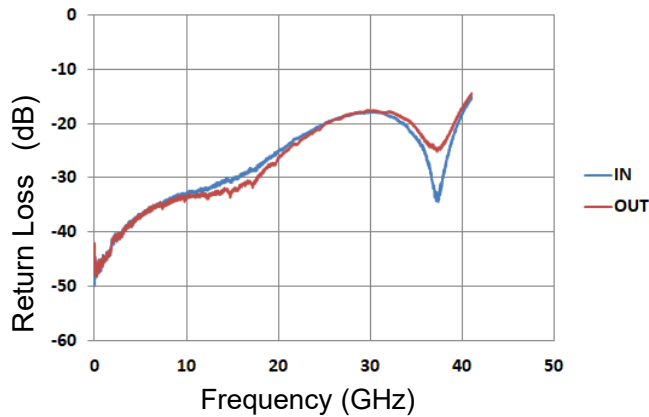
Insertion Loss @25°C



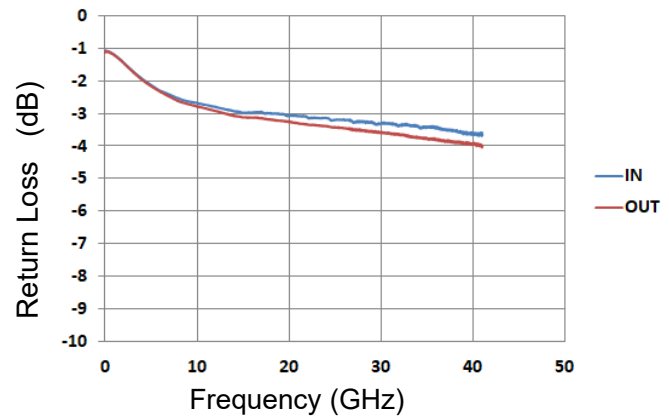
Isolation @25°C



Return Loss (ON) @25°C

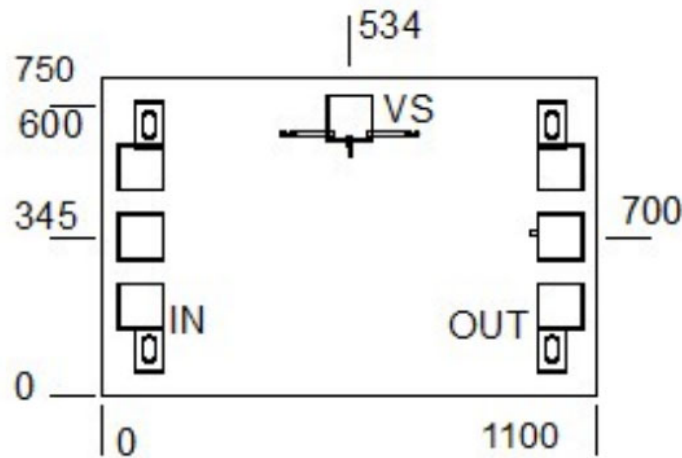


Return Loss (OFF) @25°C





Outline Drawing:
All Dimensions in mm

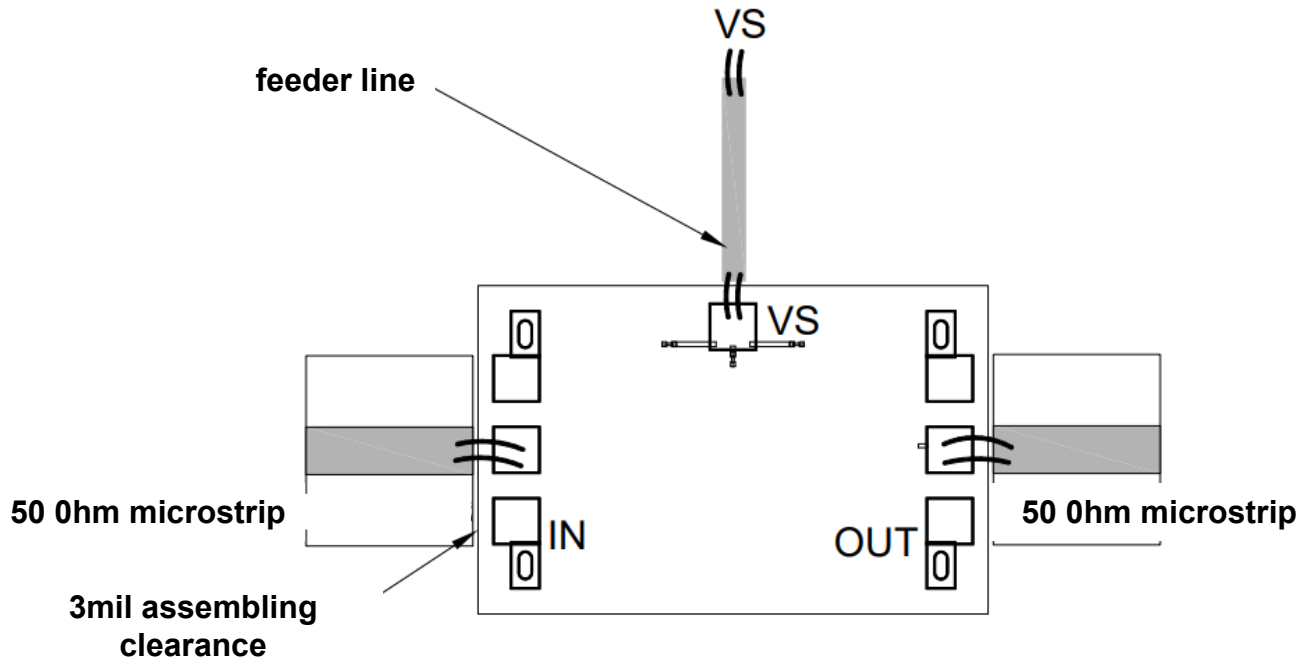


True Table

Control Voltage	State
VS	IN-OUT
0	OFF
-5	ON



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF input power: +30dBm
2. Control Voltage: -8~+1V
3. Storage temperature: -65°C to +150°C
4. Operating temperature: -55°C to 125°C